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PATENT
P57015

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

HYUN-KI PARK, et al.

Serial No.:	10/791,830	Examiner:	*To be assigned*
Filed:	4 March 2004	Art Unit:	1771

For: ELECTROMAGNETIC WAVE SHIELDING FILTER AND METHOD OF MANUFACTURING THE SAME

INFORMATION DISCLOSURE STATEMENT

Mail Stop:
Commissioner for Patents
P.O.Box 1450
Alexandria, VA 22313-1450

Sir:

In accordance with 37 C.F.R. §1.56, and §§1.97 and 1.98 as amended, Applicant cites, describes, and provides copies of the following art references:

U.S. PATENT REFERENCE:

- U.S. Patent Publication No. US-2002/0195916 to Marutsuka, entitled TRANSPARENT ELECTROMAGNETIC RADIATION SHIELD MATERIAL AND METHOD OF PRODUCING THE SAME, published 26 December 2002; and
- U.S Patent Publication No. US 2002/0050783 to Kubota et al., entitled ELECTROMAGNETIC WAVE-SHIELDING FILM, PRODUCTION METHOD THEREOF AND IMAGE DISPLAY DEVICE USING THE SAME, published 2 May 2002.

FOREIGN PATENT REFERENCE:

- European Patent Application No. EP 0963146 to Kiyama et al., entitled TRANSPARENT MEMBER FOR SHIELDING ELECTROMAGNETIC WAVES AND METHOD OF PRODUCING THE SAME, published 8 December 1999; and
- Japanese Patent Number JP 2000261187 to Yamawaki et al., entitled METHOD OF FORMING METAL PATTERN, published 22 September 2000; and
- Japanese Patent Number JP 56166059 to Katayama et al., entitled STAMPING FOIL, published 19 December 1981.

OTHER DOCUMENTS:

- European Search Report No. EP 04251192, dated 16 June 2004.

DISCUSSION

Marutsuka US'196, which was sited in the European Search Report as being of background interest as providing technological background, discusses a transparent electromagnetic radiation shield material that includes a transparent base material, an optional transparent adhesive layer on the transparent base material, and a first black layer, a metallic layer and a second black layer of identical mesh pattern successively laminated in alignment on the transparent base material, directly or via the optional transparent adhesive layer, a portion of the second black layer being removed as required.

Kubota US'783 relates to an electromagnetic-wave-shielding film, which has a transparent support and a conductive layer composed of a metal thin film, the conductive layer being composed of a mesh film in which random mesh portions are formed. An image display device, wherein the electromagnetic-wave-shielding film is mounted.

Kiyama EP'146 relates to a transparent member for use as a shield against electromagnetic waves characterized in that an electrically conductive reticular pattern is provided on a substrate (1) by forming a thin-film layer (2) of copper or an alloy thereof on the substrate by physical thin film forming means and forming a copper thick-film layer (4) on the thin-film layer by plating means so as to give the member a total transmittance of at least 50%, the reticular pattern having an electric resistivity of up to 200 mΩ/□.

Yamawaki JP'187 provides a method of forming a metal pattern which is effective for forming a light-transmissive electromagnetic shield. A conductive ink composition is coated on a film base, a photosensitive dry film for plating resist is laminated on its top layer, exposed and developed to form resist openings having a mesh pattern on the conductive ink layer, the resist openings are plated with a metal by the electroplating to form a mesh metal plating layer on the ink layer, and the metal plating pattern is buried in an adhesive layer at least twice or more as thick as the metal plating film layer to transfer it to a target base.

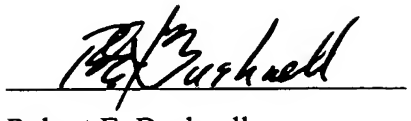
Katayama JP'059 relates to a stamping foil that is comprised of a covered layer located on the stripped-layer's surface, while the stripped-layer is located on one side of the orientational polyester film, which makes up 0.01-0.15% of the weight content that is inert material with an average particle size of 1.0-4.0μ.

Pursuant to 37 CFR § 1.97 (d), the undersigned attorney hereby certifies that each item of information contained in this Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign patent application not more than three (3) months prior to the filing of the statement.

The citation of the foregoing references is not intended to constitute an assertion that other or more relevant art does not exist. Accordingly, the Examiner is requested to make a wide-ranging and thorough search of the relevant art.

No fee is incurred by this Statement.

Respectfully submitted,



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INFORMATION DISCLOSURE STATEMENT PTO-1449 (PAGE 1 OF 1)	SERIAL NUMBER 10/791,830	DOCKET NO. P57015
	APPLICANT: HYUN-KI PARK et al.	
	FILING DATE: 4 March 2004	GROUP NO.

U.S. PATENT DOCUMENTS

EXAMINER	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLAS	FILING DATE
	US-2002/195916	12/26/02	*Marutsuka*			6/24/02
	US-2002/050783	5/2/02	*Kubota, et al*			6/1/01

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLAS	TRANSLATION YES	TRANSLATION NO
	EP0963146	12/8/99	Great Britain			Abstract	
	JP2000261187	9/22/00	Japan			Abstract	
	JP56166059	12/19/81	Japan			Abstract	

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

	Van den Bulcke, E. European Search Report, dated 16 June 2004.

EXAMINER:	*DATE CONSIDERED:*

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP §609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.